

**What is claimed is:**

1       1. An electronic device, comprising:  
2           a display unit; and  
3           a host electrically connected to the display unit,  
4           comprising a module structure having a first  
5           substrate, at least one process unit, at least one  
6           heat-dissipating device and at least one second  
7           substrate, wherein the process unit is disposed on  
8           the first substrate, and the second substrate is  
9           disposed on the first substrate relative to the  
10          process unit, and the second substrate and the  
11          first substrate have the same structure and  
12          texture.

1       2. The electronic device as claimed in claim 1, wherein  
2       the first substrate and the second substrate are formed from  
3       the same material.

1       3. The electronic device as claimed in claim 1, wherein  
2       the first substrate and the second substrate are formed by  
3       a multi-layer structure.

1       4. The electronic device as claimed in claim 1, wherein  
2       the first substrate comprises a plurality of connecting  
3       portions, and the heat-dissipating device is disposed on the  
4       connecting portions.

1       5. The electronic device as claimed in claim 1, wherein  
2       the process unit comprises CPU.

1       6. A module structure of an electronic device,  
2 comprising:

3            a first substrate;  
4            a process unit disposed on the first substrate;  
5            a heat-dissipating device disposed on the first  
6                    substrate relative to the process unit; and  
7            a second substrate disposed on the first substrate  
8                    relative to the process unit, having the same  
9                    structure and texture as the first substrate.

1       7. The module structure of the electronic device as  
2 claimed in claim 6, wherein the first substrate and the second  
3 substrate are formed from the same material.

1       8. The module structure of the electronic device as  
2 claimed in claim 6, wherein the first substrate and the second  
3 substrate are formed by a multi-layer structure.

1       9. The module structure of the electronic device as  
2 claimed in claim 6, wherein the first substrate comprises a  
3 plurality of connecting portions, and the heat-dissipating  
4 device is disposed on the connecting portions.

1       10. The module structure of the electronic device as  
2 claimed in claim 6, wherein the process unit comprises CPU.